MMZ0603AFY560VT000 High Giga Bead

Multilayer Ultra-high GHz Chip Beads

TDK's MMZ0603-V series multilayer ultra-high gigahertz chip beads are a small size solution for noise reduction in the LTE and Wi-Fi wireless spectrum and are highly effective in improving reception sensitivity in high speed mobile communication devices. This MMZ0603-V series offers high impedance at even higher frequency than the existing MMZ-E series gigahertz type chip beads. High impedance in the 2.5 to 6.0GHz frequency range is achieved by the use of a newly developed material and structure in the MMZ0603-V series.

Features

- Small size solution
- No polarity
- Excellent noise reduction in the LTE and Wi-Fi wireless spectrum
- Operating temperature range of –55°C to +125°C
- Storage temperature range of –55°C to +125°C after the circuit board is mounted

High Giga

Multilayer

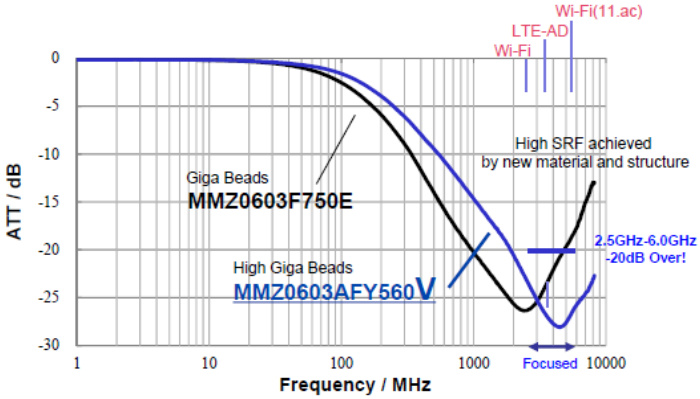
Lead Free | Halogen Free | REACH | RoHS COMPLIANT

MMZ0603-V Datasheet

Applications

- Noise removal for mobile devices such as smartphones and tablet terminals
- Smart grid & industrial equipment

Horizontal Structure of the MMZ-V Series



MMZ0603AFY560VT000 Chip Bead Information:

Case Size: 0603—0.6mm x 0.3mm x 0.3mm ± 0.03mm
Impedance at 100MHz: 56Ω ±25%
Impedance at 1GHz: 500Ω ±40%
Current Rating (max.): 125mA
DC Resistance (max.): 2.2Ω

Pieces per Reel: 15,000